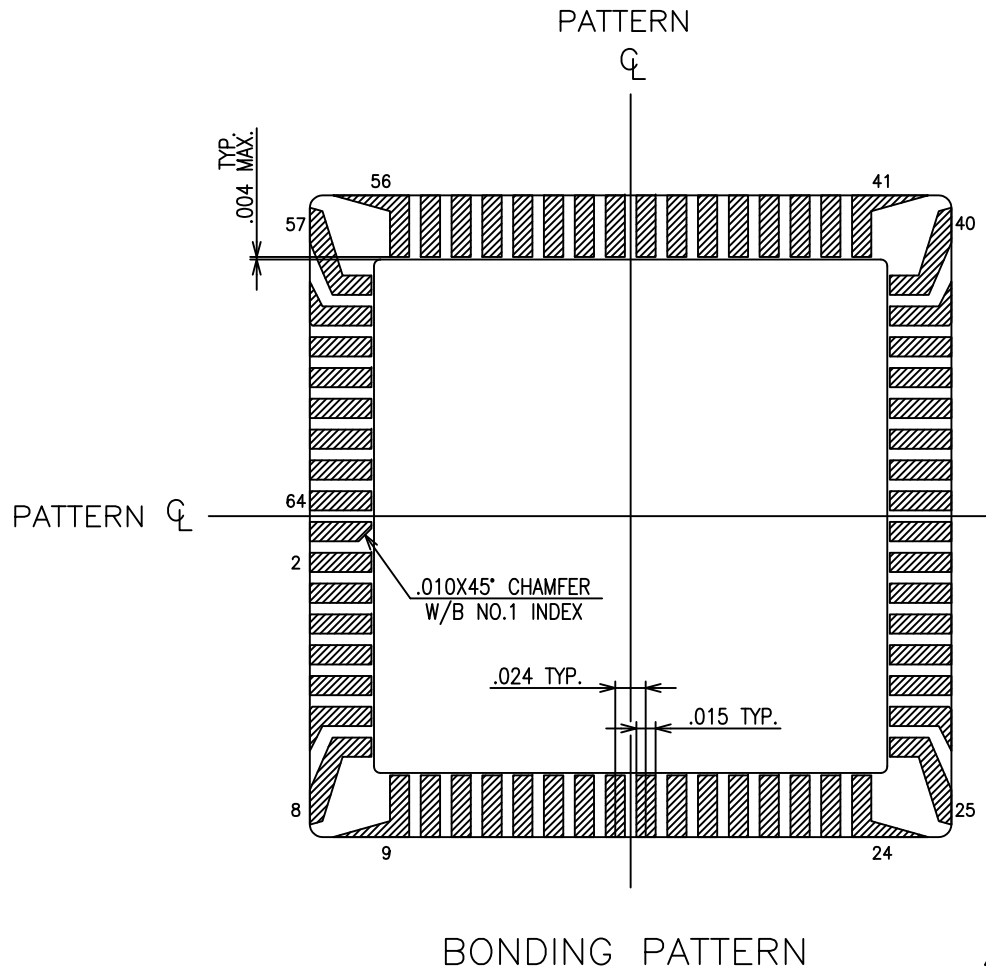


SSM P/N: CSB06428



NOTES:

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.35 OHM MAX.
6. MISALIGNMENT OF METALLIZATION PATTERN IN CAVITY SHALL BE ACCEPTED DUE TO LAYER MISALIGNMENT.
7. WIRE BOND PAD CONNECTED TO CORRESPONDED OUTER LEADS.

MODIFICATION						NAME 64 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN M.M	CHECKED K.M	APPROVED	DATE NOV.10.'83
	△	ADDED : NOTE 6,7.	APR.23.'09	S.A	H.TA/S.NI	K.IM	SCALE 10 / 1	MATERIAL			
	△	REDRAWN : CONVERTED CAD DATA.	AUG.09.'00	H.K	H.TA/S.NI	H.SA					
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION KYOTO JAPAN	THIRD ANGLE PROJECTION	DRAWING NO. KD-S83665-B		SHEET 2 / 2	

